

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 08-277486

(43)Date of publication of application : 22.10.1996

(51)Int.Cl.

C25D 5/02

C23C 26/00

C25D 7/12

C25D 21/02

H01L 23/50

(21)Application number : 07-078866

(71)Applicant : DAINIPPON PRINTING CO LTD

(22)Date of filing : 04.04.1995

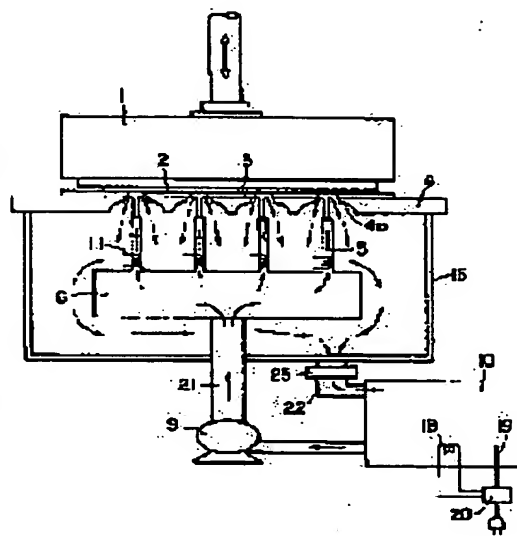
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(54) PLATING DEVICE FOR LEAD FRAME

(57)Abstract:

PURPOSE: To increase a current density and to rapidly plate a lead frame by heating a plating liquid injected from injection nozzles to this lead frame to a high temp.

CONSTITUTION: A lead frame 2 is held between a jig 4 for a mask having through-holes 4a and a press block 1. The plating liquid in a plating liquid tank 10 is introduced by a supply line 21 to injection nozzles 5 and is heated by the heaters 11 of the injection nozzles 5. The heated plating liquid is injected from the through-holes 4a of the jig 4 for mask to the lead frame 2. The plating liquid injected to the lead frame 2 is thereafter returned from the bottom of a sparger 15 through a return line 22 to the plating liquid tank 10.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

Applicants: Won-Chan Park and Chul-Min Kim
U.S. Serial No.: Not Yet Known (national stage of
PCT International Application No.
PCT/KR2004/000586)
Filed: Herewith
Exhibit 2

[Date of extinction of right]

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